WHAT IS CLAIMED IS:

1. A laminated electronic component comprising:

a plurality of parallel first conductive patterns, which are laminated via a magnetic layer to a plurality of parallel second conductive patterns, the first and second conductive patterns being alternately connected to each other via through-holes, thereby forming a spiral coil inside a laminated body, the axis of the spiral coil being parallel to a mount face; wherein

the magnetic layer, provided between the plurality of first conductive patterns and the plurality of second conductive patterns, comprises non-magnetic sections which are provided at positions corresponding to ends of the conductive patterns and extend parallel to the axis of the coil.

2. The laminated electronic component according to Claim 1, wherein

a magnetic layer is provided via a non-magnetic layer to the outer side of the plurality of first conductive patterns and the outer side of the plurality of second conductive patterns.

3. A method for manufacturing a laminated electronic component comprising a plurality of parallel first conductive patterns, which are laminated via a magnetic layer to a plurality of parallel second conductive patterns, the first and second conductive patterns being alternately connected to each other via through-holes, thereby forming a spiral coil inside a laminated body, the axis of the spiral coil being parallel to a mount face, the method comprising:

a first step of printing a plurality of first conductive patterns in parallel on a top face of a first non-magnetic layer on a first magnetic layer;

a second step of providing a second magnetic layer over the entire top face of the first non-magnetic layer, which the first conductive patterns are provided on, and providing a pair of grooves at positions corresponding to ends of the

first conductive patterns on the second magnetic layer by laser processing, the pair of grooves extending parallel to the axis of the coil;

a third step of providing non-magnetic sections having through-holes at positions corresponding to the ends of the first conductive patterns in the pair of grooves;

a fourth step of printing a plurality of second conductive patterns on the top face of the second magnetic layer, which the non-magnetic sections are provided on, the plurality of second conductive patterns being arranged in parallel so that the first conductive patterns are alternately connected thereto via the through-holes, thereby forming a spiral coil pattern; and

a fifth step of sequentially providing a second non-magnetic layer and a third magnetic layer on the second magnetic layer, which the non-magnetic sections and the second conductive patterns are provided on.

4. The laminated electronic component manufacturing method according to Claim 3, wherein

the through-holes of the third step are provided at the time of printing the non-magnetic sections in the pair of grooves.

5. The laminated electronic component manufacturing method according to Claim 3, wherein

the through-holes of the third step are provided by laser processing.

6. A method for manufacturing a laminated electronic component comprising a plurality of parallel first conductive patterns, which are laminated via a magnetic layer to a plurality of parallel second conductive patterns, the first and second conductive patterns being alternately connected to each other via through-holes, thereby forming a spiral coil inside a laminated body, the axis of the spiral coil being parallel to a mount face, the method comprising:

a first step of printing a plurality of first conductive patterns in parallel on a top face of a first non-magnetic layer on a first magnetic layer;

a second step of providing a plurality of second magnetic layers over the entire top face of the first non-magnetic layer, which the first conductive patterns are provided on, and providing a pair of grooves at positions corresponding to ends of the first conductive patterns on the second magnetic layer by laser processing, the pair of grooves extending parallel to the axis of the coil;

a third step of providing non-magnetic sections having through-holes at positions corresponding to the ends of the first conductive patterns in the pair of grooves;

a fourth step of printing a plurality of second conductive patterns on the top face of the second magnetic layer, which the non-magnetic sections are provided on, the plurality of second conductive patterns being arranged in parallel so that the first conductive patterns are alternately connected thereto via the through-holes, thereby forming a spiral coil pattern; and

a fifth step of sequentially providing a second non-magnetic layer and a third magnetic layer on the second magnetic layer, which the non-magnetic sections and the second conductive patterns are provided on.

7. The laminated electronic component manufacturing method according to Claim 6, wherein

the through-holes of the third step are provided at the time of printing the non-magnetic sections in the pair of grooves.

8. The laminated electronic component manufacturing method according to Claim 6, wherein

the through-holes of the third step are provided by laser processing.

9. A method for manufacturing a laminated electronic component comprising a plurality of parallel first conductive patterns, which are laminated via a magnetic layer to a plurality of parallel second conductive patterns, the first and second conductive patterns being alternately connected to each other via through-holes, thereby forming a spiral coil inside a laminated body, the axis of the spiral coil being

parallel to a mount face, the method comprising:

a first step of printing a plurality of first conductive patterns in parallel on a top face of a first non-magnetic layer, which is provided on a first magnetic layer;

a second step of providing a plurality of second magnetic layers having non-magnetic sections by repeatedly performing the sequential processes of providing a second magnetic layer over the entire top face of the first non-magnetic layer, which the first conductive patterns are provided on, providing a pair of grooves at positions corresponding to ends of the first conductive patterns on the second magnetic layer by laser processing, the pair of grooves extending parallel to the axis of the coil, providing non-magnetic sections having through-holes at positions corresponding to the ends of the first conductive patterns in the pair of grooves, and filling the through-holes with conductive material;

a third step of printing a plurality of second conductive patterns on the top face of the second magnetic layers having the non-magnetic sections, the plurality of second conductive patterns being arranged in parallel so that the first conductive patterns are alternately connected thereto via the through-holes,

thereby forming a spiral coil pattern; and a fourth step of sequentially providing a second non-magnetic layer and a third magnetic layer on the second magnetic layer, which the non-magnetic sections and the second conductive patterns are provided on.

10. The laminated electronic component manufacturing method according to Claim 9, wherein

the through-holes of the third step are provided at the time of printing the non-magnetic sections in the pair of grooves.

11. The laminated electronic component manufacturing method according to Claim 9, wherein

the through-holes of the third step are provided by laser processing.